No.: RPC-K-HTS-0002 /8

Date: 2017. 4. 21

Data sheet

FIXED THICK FILM CHIP RESISTORS;
RECTANGULAR TYPE AND ANTI SURGE

Style: RPC16, 20, 32, 35, 50, 63

AEC-Q200 qualified

RoHS COMPLIANCE ITEM Halogen and Antimony Free

Note: •Stock conditions

Temperature: +5°C ~ +35°C Relative humidity: 25% ~ 75%

The period of guarantee: Within 2 year from shipmen t by the company.

Solderability shall be satisfied.

- Product specification contained in this data sheet are subject to change at any time without notice
- •If you have any questions or a Purchasing Specification for any quality Agreement is necessary, please contact our sales staff.



Hokkaido Research Center Approval by: T. Sannomiya Drawing by: M. Shibuya

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Title: FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND ANTI SURGE

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1. Scope

1.1 This data sheet covers the detail requirements for fixed thick film chip resistors; rectangular type & anti surge, style of RPC16, 20, 32, 35, 50, 63.

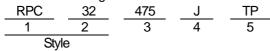
1.2 Applicable documents

JIS C 5201-1: 2011, JIS C 5201-8: 2014, JIS C 5201-8-1: 2014 IEC60115-1: 2008, IEC60115-8: 2014, IEC60115-8-1: 2014 EIAJ RC-2134C-2010

2. Classification

Type designation shall be the following form.

(Example)



1 Fixed thick film chip resistors; rectangular type and anti surge

2 Size

3 Rated resistance

475	E24 Series, 3 digit,	Ex. 475> $4.7M\Omega$,
-----	----------------------	-------------------------

4 Tolerance on rated resistance

J	±5%
K	±10%
М	±20%

5 Packaging form

99	
В	Bulk (loose package)
TP	Paper taping
TE	Embossed taping

3. Rating

3.1 The ratings shall be in accordance with Table-1.

Table-1(2)

Style	Rated dissipation (W)	Temperature coefficient of resistance (10 ⁻⁶ /°C)	Rated resistance range(Ω)	Preferred number series for resistors	Tolerance on rated resistance	
RPC16	0.25	±100	10~1M	E24	J(±5%)	
0.0	0.20	±200	1.0~9.1		3(=370)	
		±200	1.1M~22M			
RPC20	0.25	±100	1.0~1M	E24	J(±5%), K(±10%), M(±20%)	
		±200	0.27~0.91			
		±200	1.1M~22M			
RPC32	0.33	±100	1.0~1M	E24	J(±5%), K(±10%), M(±20%)	
		±200	0.27~0.91			
		±200	1.1M~22M			
RPC35	0.5	±100	1.0~1M	E24	J(±5%), K(±10%), M(±20%)	
		±200	0.27~0.91			
		±200	1.1M~22M			
RPC50	0.75	±100	1.0~1M	E24	J(±5%), K(±10%), M(±20%)	
		±200	0.27~0.91			
		±200	1.1M~22M			
RPC63	1.0	±100	1.0~1M	E24	J(±5%), K(±10%), M(±20%)	
		±200	0.27~0.91			

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Table-1(2)

Style	Limiting element voltage (V)	Isolation voltage (V)	Category temperature range (°C)
RPC16	150	150	
RPC20	150		
RPC32			FE .4FE
RPC35	200	500	<i>–</i> 55∼+155
RPC50	200		
RPC63			

3.2 Climatic category

55/155/56 Lower category temperature -55 °C
Upper category temperature +155 °C
Duration of the damp heat, steady state test 56days

3.3 Stability class

5% Limits for change of resistance:

 $\begin{array}{ll} -\text{for long-term tests} & \pm (5\% + 0.1 \Omega) \\ -\text{for short-term tests} & \pm (1\% + 0.05 \Omega) \end{array}$

3.4 Derating

The derated values of dissipation at temperature in excess of 70 °C shall be as indicated by the following curve.

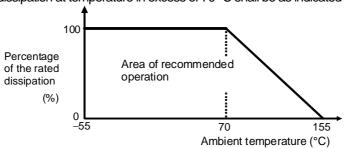


Figure-1 Derating curve

3.5 Rated voltage

d. c. or a. c. r. m. s. voltage calculated from the square root of the product of the rated resistance and the rated dissipation.

Limiting element voltage can only be applied to resistors when the resistance value is equal to or higher than the critical resistance value.

At high value of resistance, the rated voltage may not be applicable.

4. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

Symbol	Packaging form		Standard packaging quantity / units	Application
В	Bulk (loose package)	1,000 pcs.	RPC16, 20, 32, 35, 50, 63
TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.	RPC16, 20, 32
TE	Embassed tening	8mm width, 4mm pitches	4.000 p.co	RPC35
TE	Embossed taping 12mm width, 4mm pitches	4,000 pcs.	RPC50, 63	

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5. Dimensions

5.1 The resistor shall be of the design and physical dimensions in accordance with Figure-2 and Table-3.

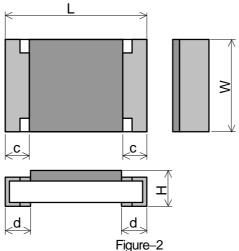


Figure-2 Table-3

Table-3				Unit: mm	
Style	L	W	Н	С	d
RPC16	1.6±0.1	0.8 +0.15 -0.05	0.45±0.10	0.3±0.2	0.3±0.1
RPC20	2.0 ± 0.1	1.25 ± 0.10	0.55 ± 0.10		0.4 ± 0.2
RPC32	3.1 ± 0.1	1.6 ± 0.15	0.55 ± 0.10	0.3 ± 0.2	0.5 ± 0.25
RPC35	3.1 ± 0.15	2.5 ± 0.15			0.5 ± 0.25
RPC50	5.0 ± 0.15	2.5 ± 0.15	0.55 ± 0.15	0.3 ± 0.15	0.6 ± 0.2
RPC63	63+015	32+015		0.5 ± 0.15	0.0 ± 0.2

5.2 Net weight (Reference)

Style	Net weight(mg)
RPC16	2
RPC20	5
RPC32	9
RPC35	16
RPC50	25
RPC63	40

6. Marking

The Rated resistance shall be marked in 3 digits (E24) and marked on over coat side.

Marking example	Contents	Application
123	$12\times10^3 \ [\Omega] \rightarrow 12 \ [k\Omega]$	E24
2R2	2.2 [Ω]	E24

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7. Performance

7.1 The standard condition for tests shall be in accordance with Sub-clause 4.2, JIS C 5201–1: 2011.

7.2 The performance shall be satisfied in Table-4.

Table-4(1)

No.	Test items	Condition of test (JIS C 5201–1)	Performance requirements
1	Visual examination	Sub-clause 4.4.1	As in 4.4.1
'		Checked by visual examination.	The marking shall be legible, as
		Shooked by Houdi Grainii Idlienii	checked by visual examination.
2	Dimension	Sub-clause 4.4.2	As specified in Table-3 of this
			specification.
	Resistance	Sub-clause 4.5	As in 4.5.2
			The resistance value shall
			correspond with the rated resistance
			taking into account the specified
) / / /		tolerance.
3	Voltage proof	Sub-clause 4.7	No baselules as alforb essen
		Method: 4.6.1.4(See Figure–5)	No breakdown or flash over
		Test voltage: Alternating voltage with a peak value of 1.42 times the insulation	
		value of 1.42 times the insulation voltage.	
		Duration: 60 s ± 5 s	
		Insulation resistance	R≥1GΩ
		Test voltage: Insulation voltage	
		Duration: 1 min.	
4	Solderability	Sub-clause 4.17	As in 4.17.4.5
		Without ageing	The terminations shall be covered
		Flux: The resistors shall be immersed in a	with a smooth and bright solder
		non-activated soldering flux for 2s.	coating.
		Bath temperature: 235 °C ± 5 °C	
_	B.A	Immersion time: 2 s ± 0.5 s	
5	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure–3 Sub–clause 4.13	
	Overload	The applied voltage shall be 2.5 times the rated	
	(in the mounted state)	voltage or twice the limiting element voltage,	
	,	whichever is the less severe.	
		Duration: 2 s	
		Visual examination	No visible damage
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
	Solvent resistance of the	Sub-clause 4.30	Legible marking
	marking	Solvent: 2-propanol	
		Solvent temperature: 23 °C ± 5 °C	
		Method 1	
		Rubbing material: cotton wool	
		Without recovery	

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FIXED THICK FILM CHIP RESISTORS; RECTANGULAR TYPE AND ANTI SURGE

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Table 4(2)

		Table—4(2)	
No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
6	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure-4	
	Bound strength of the end	Sub-clause 4.33	
	face plating	Bent value: 3 mm (3225 size max.)	
		1 mm (5025 size min.)	
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
	Final measurements	Sub-clause 4.33.6	No visible damage
		Visual examination	
7	Resistance to soldering heat	Sub-clause 4.18	
		Solder temperature: 260 °C ± 5 °C	
		Immersion time: $10 \text{ s} \pm 0.5 \text{ s}$	
		Visual examination	As in 4.18.3.4
			No sign of damage such as cracks.
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
	Component solvent	Sub-clause 4.29	
	resistance	Solvent: 2-propanol	
		Solvent temperature: 23 °C ± 5 °C	
		Method 2	
		Recovery: 48 h	
		Visual examination	No visible damage
		Resistance	$\Delta R \le \pm (1\% + 0.05\Omega)$
8	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		Test substrate: Figure–3	
	Adhesion	Sub-clause 4.32	
		Force: 5 N	
		Duration: $10 s \pm 1 s$	
	Day'd door to see and a	Visual examination	Nie 2-1 ie de cent
	Rapid change temperature	Sub-clause 4.19	No visible damage
		Lower category temperature:-55 °C	
		Upper category temperature:+155 °C	
		Duration of exposure at each temperature:	
		30 min.	
		Number of cycles: 5 cycles.	No visible damage
		Visual examination	No visible darriage $\Delta R \le \pm (1\% + 0.05\Omega)$
		Resistance	$\Delta \Gamma \geq \pm (1.70 \pm 0.0052)$

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Table-4(3)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
9	Climatic sequence	Sub-clause 4.23	
	-Dry heat	Sub-clause 4.23.2	
		Test temperature: +155 °C	
		Duration: 16 h	
	–Damp heat, cycle	Sub-clause 4.23.3	
	(12+12hour cycle)	Test method: 2	
	First cycle	Test temperature: 55 °C	
		[Severity(2)]	
		Sub-clause 4.23.4	
	-Cold	Test temperature –55 °C	
		Duration: 2h	
		Sub-clause 4.23.6	
	–Damp heat, cycle	Test method: 2	
	(12+12hour cycle)	Test temperature: 55 °C	
	Remaining cycle	[Severity (2)]	
		Number of cycles: 5 cycles	
		Sub-clause 4.23.7	
	–D.C. load	The applied voltage shall be the rated voltage	
		or the limiting element voltage whichever is the	
		smaller.	
		Duration: 1 min.	No visible damage
		Visual examination	$\Delta R \le \pm (5\% + 0.1\Omega)$
		Resistance	ΔI(≤ ± (5 /0+0.122)
10	Mounting	Sub-clause 4.31	
		Substrate material: Epoxide woven glass	
		(RPC63 may use Alumina substrate.)	
	F. J	Test substrate: Figure–3	
	Endurance at 70 °C	Sub-clause 4.25.1	
		Ambient temperature: 70 °C ± 2 °C	
		Duration: 1000 h	
		The voltage shall be applied in cycles of 1.5 h	
		on and 0.5 h.	
		The applied voltage shall be the rated voltage	
		or the limiting element voltage whichever is the	
		smaller.	
		Examination at 48 h, 500 h and	
		1000 h: Visual examination	No visible damage
			$\Delta R \le \pm (5\% + 0.1\Omega)$
		Resistance	△(C / C / C / C / C / C / C / C / C / C /

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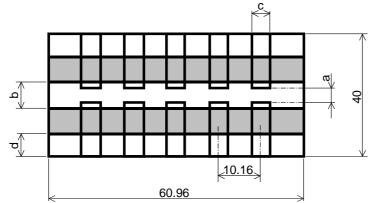
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Table-4(4)

No	Test items	Condition of test (JIS C 5201–1)	Performance requirements
11	Mounting Variation of resistance with temperature	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure–3 Sub-clause 4.8 -55 °C / +20 °C +20 °C / +155°C	As in Table–1
12	Mounting Damp heat, steady state	Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure—3 Sub-clause 4.24 Ambient temperature: 40 °C ± 2 °C Relative humidity: 93 ½ % a) 1st group: without voltage applied. b) 2nd group: The d. c. voltage shall be applied continuously. The voltage shall be accordance with Sub-clause 4.24.2.1 b). without polarizing voltage [4.24.2.1, c)] Visual examination Resistance	No visible damage Legible marking $\Delta R \leq \pm (5\% + 0.1\Omega)$
13	Dimensions (detail) Mounting Endurance at upper category temperature	Sub-clause 4.4.3 Sub-clause 4.31 Substrate material: Epoxide woven glass Test substrate: Figure-3 Sub-clause 4.25.3 Ambient temperature:155 °C ±2 °C Duration: 1000 h Examination at 48 h, 500 h and 1000 h: Visual examination Resistance	As in Table–3 No visible damage $\Delta R \le \pm (5\%+0.1\Omega)$

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8. Test substrate



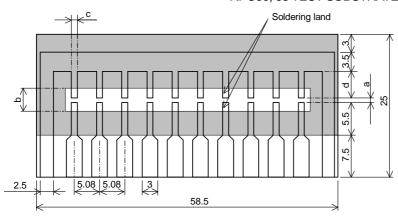
Unit: mm

:Copper clad

:Solder resist

Style	а	b	С	d
RPC50	4.0	7.5	2.0	7.5
RPC63	5.0	9.0	4.5	7.5

RPC50, 63 TEST SUBSTRATE



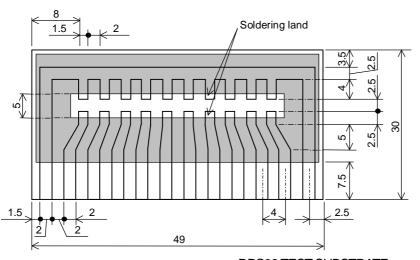
Unit: mm

:Copper clad

:Solder resist

Style	а	b	С	d
RPC20	1.2	4.0	1.5	4.3
RPC35	2.2	5.0	2.9	3.3

RPC20, 35 TEST SUBSTRATE



Unit: mm

:Copper clad

:Solder resist

RPC32 TEST SUBSTRATE

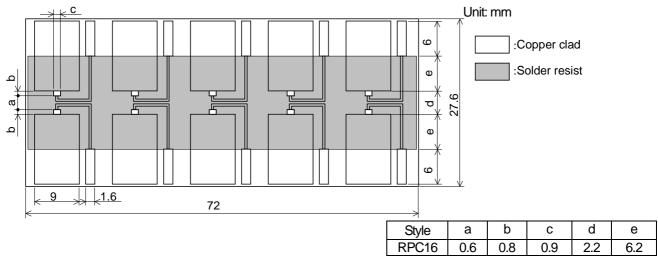
Figure-3(1)

Remark 1). Material: Epoxide woven glass

Thickness: 1.6mm Thickness of copper clad: 0.035mm

2). In the case of connection by connector, the connecting terminals are gold plated. However, the plating is not necessary when the connection is made by soldering.

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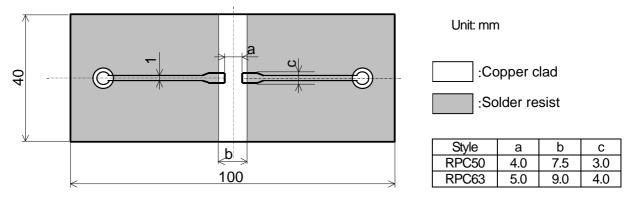
RPC16 TEST SUBSTRATE

Figure-3(2)

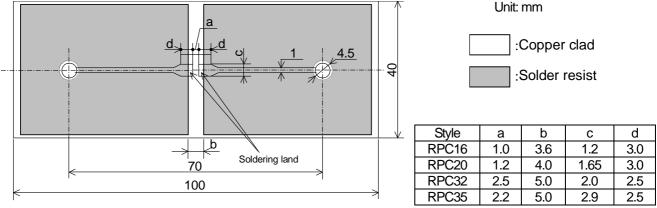
Remark 1). Material: Epoxide woven glass

Thickness: 1.6mm Thickness of copper clad: 0.07mm

2). In the case of connection by connector, the connecting terminals are gold plated. However, the plating is not necessary when the connection is made by soldering.



RPC50, 63 BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

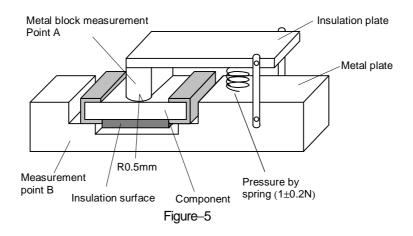


Remark 1). Material: Epoxide woven glass

Thickness: 1.6mm Thickness of copper clad: 0.035mm

RPC16,20,32,35 BOUND STRENGTH OF THE END FACE PLATING TEST SUBSTRATE

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9. Taping

- 9.1 Applicable documents JIS C 0806-3: 2014, EIAJ ET-7200C: 2010
- 9.2 Taping dimensions
- 9.2.1 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-6 and Table-5.

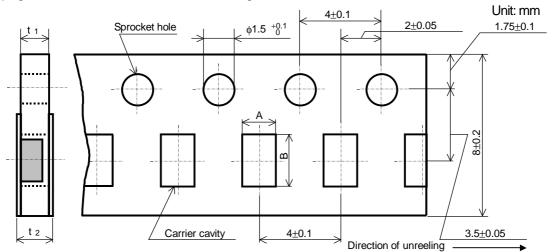
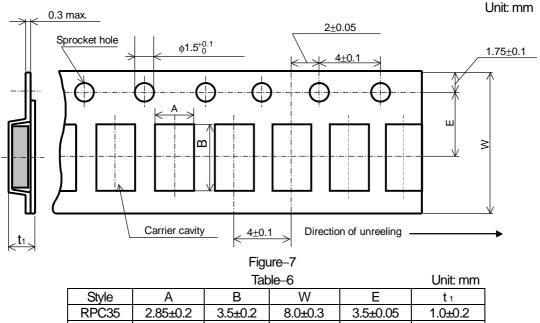


Figure-6

g .					
	Unit: mm				
Style	Α	В	t 1	t 2	
RPC16	1.15 ± 0.15	1.9 ± 0.2	0.6 ± 0.1	0.8max.	
RPC20	1.65±0.15	2.5±0.2	0.8±0.1	1.0max.	
RPC32	2.00±0.15	3.6±0.2	0.0±0.1	1.0Hax.	

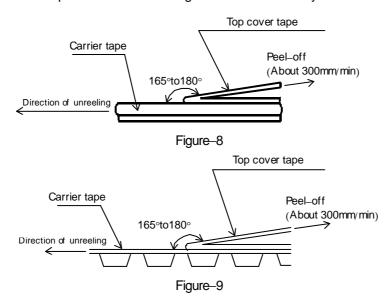
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9.2.2 Embossed taping dimensions shall be in accordance with Figure-7 and Table-6.



		10000			Orna min
Style	Α	В	W	Е	t 1
RPC35	2.85±0.2	3.5±0.2	8.0±0.3	3.5±0.05	1.0±0.2
RPC50	3.1±0.2	5.5±0.2	12.0±0.3	5 5 10 OF	1 1 1 0 15
RPC63	3.6±0.2	6.9±0.2	12.0±0.3	5.5±0.05	1.1±0.15

- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following RPC16, 20, 32: Figure-8, RPC35, 50, 63: Figure-9.
- 6). When the tape is bent with the minimum radius for RPC16, 20, 32, 35: 25 mm, or RPC50, 63: 30 mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- 7). In no case shall there be two or more consecutive components missing. The maximum number of missing components shall be one or 0.1%, whichever is greater.
- 8). The resistors shall be faced to upward at the over coating side in the carrier cavity.



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9.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure–10 and Table–7. Plastic reel (Based on EIAJ ET–7200C)

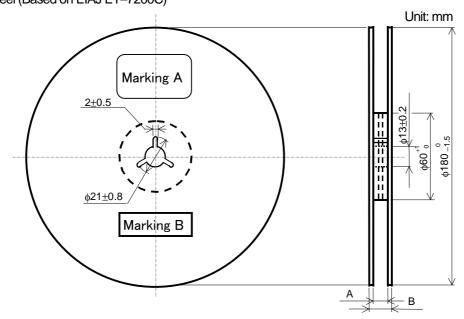
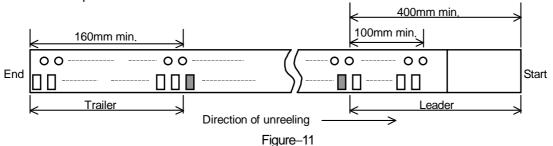


Figure-10

	Table-	-7	Unit: mm	
Style	Α	В	Note	
RPC16,20,32,35	9 +1.0	11.4±1.0	Injection molding	
NF C 10,20,32,33	9 0	13±1.0	Vacuum forming	
RPC50,63	13 ^{+1.0}	17±1.0	Vacuum forming	

Note: Marking label shall be marked on a place of Marking A or two place of Marking A and B.

9.4 Leader and trailer tape.



10. Marking on package

The label of a minimum package shall be legibly marked with follows.

10.1 Marking A

- (1) Classification (Style, Rated resistance, Tolerance on rated resistance, Packaging form)
- (2) Quantity (3) Lot number (4) Manufacturer's name or trade mark (5) Others
- 10.2 Marking B (KAMAYA Control label)